



**TECHNICAL CHARACTERISTICS**

**1.General Characteristics**

Dimensions:55.50Lx40.00Wx5.80H mm  
 Weight:Approx11.5±0.5g  
 Contact principle:Landing technology  
 Operating positions:shaft up/down/horizontal  
 Mounting System:DIP type  
 Durability:300,000 cycles min.

**2.Mechanical characteristics:**

Insulation material:Thermoplastic,UL 94V-0

**3.Electrical Characteristics**

Number of contacts (Optional):8 pins  
 contact resistance:50mΩtypical,100mΩmax  
 insulation resistance:>1000MΩ/500V DC

**4.Solderability**

Wave:260°C,5Sec:Max.  
 Vaporphase:Not applicable  
 IR reflow: Not applicable  
 Manual soldering :360°C,3sec:Max

**5.Environmental Characteristics**

Operating temperature: -40°C~+85°C  
 Operating humidity :10%~+95%RH  
 Storage temperature:-40°C~+85°C  
 storage Humidity:10%~95%RH  
 thermal Shock:-40°C~+85°C,5cycles  
 Damp Heat:40°C,90%RH,10days.  
 Salt-Mist:35°C,5%NaCl,24HR

**Wellco T&C Co., Ltd.**

**Smart Card Acceptor**

**Model No: -C822(DIP)**

**Normally open (Landing)**

**REVISION:1.0 DATE: Apr .10.2005**